No. 5, Jalan Satria 24, Taman Satria, Bt. 10 Kebun Bharu, 42500 Telok Panglima Garang, Selangor.

Phone Number (HP): +60122774344 Email Address: elmisawal@yahoo.com



## MOHAMAD ELMI MD. SAWAL

## PERSONAL OBJECTIVE

To exceed the expectations of the company and self targets to provide for the overall profitability of the company, by meeting the specific technical and quality requirements and achieve personal satisfaction from the knowledge gained and a job well done.

EDUCATIONAL BACKGROUND		
LEVEL	INSTITUTION	FIELD
University	University Science of Malaysia	B.Eng (Honours) Electrical
(2000-2004)	(USM)	Engineering

WORK EXPERIENCE		
POSITION/	RESPONSIBILITY	SKILLS
DEPARTMENT		
Process Engineer	1. Conducting study and implement	1. Failure Mode
(Plate)	improvements or cost saving of raw material	Effect & Analysis
	used in production.	2. Root cause
Metek Kitamura	2. Leading on evaluating required plating	analysis
(M) Sdn. Bhd.	characteristic on new customer product.	3. Presentation
(Telok Panglima	3. Troubleshoot process abnormality and product	4. 8D-Reports
Garang Branch)	quality issue through detail investigation and	5. Figure-of-Eight
	simulation.	Problem Solving
Jun 2004 ~ Sep	4. Coordinating and monitoring product turn	6. Internal Auditing
2008	around time meets customer requirement.	7. SPC monitoring
	5. Leading Kobetsu Kaizen activity through	8. Microsoft Office
	collaboration with customer focusing major	Applications
	quality issue.	(Words, Excel,
	6. Conduct training for new and revised	PowerPoint)
	procedure to production floor.	9. Solid Edge v19
	7. Maintaining and review documentation related	10. Basic PLC
	to production, handling and process.	11. Waste
	8. Response to any quality spill to customer,	Management
	feedback to production floor and feed forward	12. Chemical
	to management on the details issue, initial	Calculation &
	finding and containment action offered. Full	Process Control
	8D report submitted after effectiveness of	
	corrective action implemented.	
	9. Certified Internal Auditor for ISO 14001 :	
	2004 and ISO 9001 : 2000	
Quality Assurance	Maintain and periodical review	1. Failure Mode
Engineer	documentation that related to production and	Effect & Analysis
(Operation)	process.	2. Root cause
	2. Strive to accomplished target on QA Indices	analysis
Sensata	(Lot Acceptance rate, Hold Lot, Machine	3. Presentation
Technologies (M)	Shutdown, Operator Compliance,	4. 8D-Reports

Sdn. Bhd.	Containment Elimination, Cost of Poor	5. Internal Auditing
	Quality reduction and Abnormality Control	6. SPC monitoring
Sep 2008 ~ Oct	compliance) through frequent monitoring and	7. Microsoft Office
2011	follow-up.	Applications
	3. Coordinate Reject Material Return (RMR)	(Words, Excel,
	and Finished-Good Hold (FG-Hold)	PowerPoint).
	disposition flow, in-process, accomplishment	8. Minitab
	and Oracle transaction then communicate	Application
	with Material Review Board (MRB) for	<ol><li>SQL Server</li></ol>
	acceptance purpose before ship to customer.	Analyzer
	4. Lead & coordinate Yield Loss Control and	10. Measurelink
	containment at Back End process, through	Application
	collaboration with manufacturing, process	11. APIS
	and equipment engineering, communicate and	12. Lean
	react through Performance Excellence Team	Manufacturing
	(PET) meeting by weekly and Management	13. Six Sigma
	Operation Review Meeting (monthly).	14. Oracle
	5. Leading on containment elimination and	15. Matrix
	monitoring of cost of poor quality by	16. Agile
	coordinating and following-up on related	17. SAP
	corrective action needed with regards to	
	related internal and external quality issue.	
Sr. Quality	1. Responsible of Incoming & In-process Quality	Failure Mode
Assurance	for Surface Mount Supplies (SMS) operation	Effect & Analysis
Engineer	and Interconnect Assembly operation.	2. Root cause
	2. Leading and coordinating In-Process Quality	analysis
3M Seremban (M)	audit enhancement through close	3. Presentation
Sdn. Bhd.	collaboration with Manufacturing and	4. 8D-Reports
	Engineering on audit findings closure and	5. Internal Auditing
Oct 2011 ~	weekly monitoring the issue and progress.	6. SPC monitoring
Present	3. Leading and coordinating Outsource's	7. Microsoft Office
	(Interconnect Assembly Operations)	Applications
	Customer Satisfaction Scorecard	(Words, Excel,
	establishment and execution	PowerPoint).
	through monthly process audit and weekly	8. Minitab
	follow-up on issue's closure.	Application
	4. Leading and coordinating on total plant	9. Lotus Notes
	Calibration of QA Equipment and	Application
	Measurement System Analysis (MSA) on	10. Lean Six Sigma
	both Equipment and People capability.	11. QMS ISO 9001
	5. Leading Q-Hold inventory monitoring in	Lead Auditor
	warehouse for all hold items and follow-up on	
	disposition and closure required from	
	responsible person.	
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MAJOR AC	CCOMPLISHMENT / RECOGNITIONS
YEAR	ACCOMPLISHMENT / AWARDS
2004	Completion of SnBi plating evaluation (evaluation, initial phase, initial
	control & pre-launch stages) for customer's related product and packages
	leading to business income increased by 30% for 4Q04.
2005	Establishing effective reaction flow and SPC monitoring on new install of
2002	SL02 Online Monitoring for current and voltage at SL02 machine.
2005	Team member of MKM's QCD Team for cost down activity in operation with
	achievement of reduction by 20K/month on raw material and spare part
	consumption.
2006	Member of machine buyoff team for new concept of Water Jet at Incheon,
	Korea for SL03 machine – Reflecting improvement on Resin Remain and
	Plating Peel Off defect.
2006	Successfully eliminating Abnormal Growth recurrence (average occurrence :
	5 lots per month for 1H06) reflection of zero occurrences on 2H06 through
	Task Force formation and continuous evaluation, follow-up and monitoring.
	This defect is dangerous which can lead to lead-interspacing due to abnormal
	stress on plating surface.
2007	Accomplished Solder Particle improvement for FY2007 with reduction of the
	defect from 0.53% to 0.1% monthly through execution of Key Control Point
	and task force team.
2007	Kobetsu Kaizen Bronze Medal (NEC Semiconductor competition) –
	Reduction of Bent & Damaged Lead Frames at Plating Tank from 70ppm to
	10ppm with impact reduction of losses by RM 1.5k/month.
2008	Execution on Key Control Point and task force team and successfully
	achieved reduction of Bent & Damaged Lead Frames from 0.01% (2H07) to
	0.005% (1H08).
2008	Kobetsu Kaizen Bronze Medal (NEC Semiconductor competition) –
	Reduction of Bent & Damaged Lead Frames from 300ppm to 115ppm (more
2000	than 50% reduction) with impact reduction of losses by RM 12k/month.
2008	SL04 Pure Tin New Machine Setup & SL03 machine conversion from SnPb
2000	plating to SnBi plating. – increase productivity and product leadtime  Member of RMR sensor material which salvaged suspected crack capacitance
2009	units through evaluation and analysis which save cost by USD 30k.
2009	Member of new Snap 5 Qualification machine, a 7-up snap machine created
2007	to reduce impact on PCB which affected to improvement on crack
	capacitance.
2010	Leading Small Group Activity on cracked capacitance issue by coordinating
2010	weekly meeting and follow-up items with significant scrap cost saves by USD
	120k / year.
2011	Leading Lean Manufacturing project on removing QC pack and headcounts
	reduce with headcounts cost saves at USD 17.4k / year.
2011	Leading Containment Elimination activity with current status of cost of poor
	quality at 30% reduction costs USD 10k / month.
2011	Technical Paper 'P1Cap Limit Optimization' based on DMAIC approached
	submitted with successfully implemented and saves scrap cost at USD 100k/
	year.
2011	Leading and coordinating MSA completion for MSG line for 2011 TS Audit.
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2012	Leading and coordinating In-Process Quality Audit kick-off and enhancement
	for Surface Mount Supplies (SMS) operation which included as part of
	Corporate plan on 50% Quality Incident reduction.
2012	Leading and coordinating on the establishment of MSA Variable / Attributes
	for overall manufacturing plant.

2012	Leading and coordinating 50% Quality Incident reduction at Outsource's
	Plant.
2013	Leading in establishing QA training module and structure for SMS
	production.
2013	Leading in improvement of eNPR process flow and system in Lotus Notes
	which increased productivity by 35%.
2013	Leading in improvement of IAR / CPAR process flow and system for SMS
	which increased productivity by 20%.

TRAINING AND DEVELOPMENT	
YEAR	COURSE
Apr-13	Hazard Identification, Risk Analysis & Risk Control for OHSAS 18001
Apr-13	Environmental Aspect Impact Analysis for ISO 14001
Apr-13	IRCA Lead Auditor for ISO 9001
Mar-13	Line Leader Development
Aug-12	Technical Aspect in Calibration System
Aug-12	Lean Six Sigma: Lean Training (Kaizen, VSM, DOE, Lean, PM)
May-12	Lean Six Sigma: Green Belt (DMAIC)Training
Mar-12	Lean Six Sigma: Product & Process Understanding (PPU)
Apr-11	AGILE : Change Management
Apr-11	VDA 6.3 Internal Audit
Mar-11	ISO/TS 16949 : 2009 Advanced Internal Auditing
Jan-11	Basic SQL / Minitab Training
Nov-10	Root Cause Analysis
Jul-09	Total Quality Culture
May-09	Cost of Quality
Dec-08	Global Change Management
Jul-08	ISO/TS 16949 : 2002 Internal Auditing
Oct-07 ~ Mar-08	ISO/TS 16949 : 2002 Core Tool Training (APQP,FMEA,SPC & MSA)
Sep-07	ISO/TS 16949 : 2002 Awareness Training
Aug-07	ISO 14001 : 2004 Internal Auditing
Aug-06	ISO 9001 : 2000 Internal Auditing
Aug-05	Train The Trainer

## AVAILABILITY 1 Month Notice

REFERENCE	
REF 1	
Name	Azrul Faizal Mohamad Dahalal
Designation	Manager (Quality), Sensata Technologies (M) Sdn. Bhd.
Contact No.	+60192192003
REF 2	
Name	Ragu Simathari
Designation	Sr. Manager (Manufacturing), Sensata Technologies (M) Sdn. Bhd.
Contact No.	+60126162867
REF 3	
Name	Mohd Shaharudin Mohd Shariff
Designation	Manager (Quality), 3M Seremban (M) Sdn. Bhd.
Contact No.	+60123770157